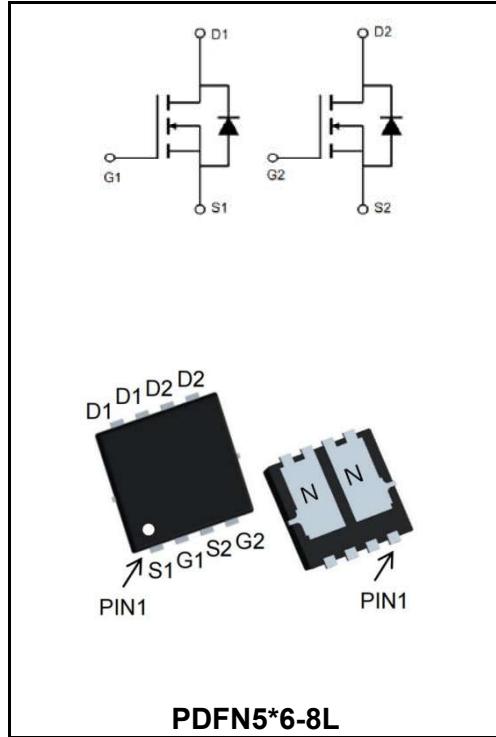


60V N+N-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

I_D	70A
V_{DSS}	60V
$R_{DS(on)-typ}(@V_{GS}=10V)$	< 10mΩ (Type: 7.5 mΩ)


Features

- ◆ YFW-SGT technology

Application

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

Product Specification Classification

Part Number	Package	Marking	Pack
YFWG70H06NF	PDFN5*6-8L	YFW 70H06NF XXXXX	5000PCS/Tape

Maximum Ratings at $T_c=25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	60	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current @ $T_A=25^\circ\text{C}$	I_D	70	A
Continuous Drain Current @ $T_A=70^\circ\text{C}$	I_D	45	A
Pulsed Drain Current	I_{DM}	280	A
Power dissipation @ $T_A=25^\circ\text{C}$	P_D	60	W
Single Pulse Avalanche Energy	E_{AS}	30	mJ
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C
Thermal Resistance ,Junction-Case	$R_{\theta JC}$	2.1	°C/W
Thermal resistance, junction-ambient5)	$R_{\theta JA}$	25	°C/W

Maximum Ratings at T_c=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	B _{VDSS}	60	68	-	V
Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	V _{GS(th)}	1.2	1.5	2.5	V
Drain-source on-state resistance	V _{GS} =10V, I _D =20A	R _{DS(ON)}	-	7.5	10	mΩ
	V _{GS} =4.5V, I _D =10A		-	10	13	
Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	I _{GSS}	-	-	±100	nA
Drain-Source Leakage Current	V _{DS} =60V, V _{GS} =0V	I _{DSS}	-	-	1	uA
Input Capacitance	V _{GS} =0V V _{DS} =50V f=100 kHz	C _{iss}	-	1182.1		pF
Output Capacitance		C _{oss}	-	199.5		
Reverse Transfer Capacitance		C _{rss}	-	4.1		
Turn-on delay time	V _{GS} =10V V _{DD} =50V R _G = 2Ω I _D = 10A	t _{d(on)}	-	17.9	-	ns
Rise Time		T _r	-	4.0	-	
Turn-Off Delay Time		t _{d(OFF)}	-	34.9	-	
Fall Time		t _f	-	5.5	-	
Total Gate Charge	I _D =10A V _{DS} =50V V _{GS} =10V	Q _g	-	18.4	-	nC
Gate-Source Charge		Q _{gs}	-	3.3	-	
Gate-Drain Charge		Q _{gd}	-	3.1	-	
Gate plateau voltage		V _{plateau}		2.8		
Diode forward current	V _{GS} <V _{th}	I _s		-	60	A
Pulsed Source Current		I _{SP}		-	180	
Diode Forward Voltage	I _s =20A , V _{GS} =0V	V _{SD}	-	-	1.3	V
Reverse Recovery Time	I _s =10A , dI/dt=100A/μs	t _{rr}	-	41.8	-	nS
Reverse Recovery Charge		Q _{rr}	-	36.1	-	nC
Peak reverse recovery current		I _{rrm}		1.4		A

Note

1. Calculated continuous current based on maximum allowable junction temperature.
2. Repetitive rating; pulse width limited by max. junction temperature.
3. Pd is based on max. junction temperature, using junction-case thermal resistance.
4. V_{DD}=50 V, R_G=50 Ω, L=0.3 Mh , starting T_j=25 °C.
5. The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with Ta=25 °C.

Ratings and Characteristic Curves

Typical Characteristics

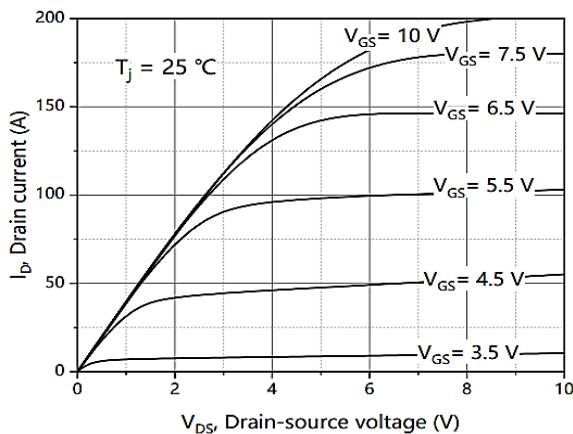


Figure 1. Typ. output characteristics

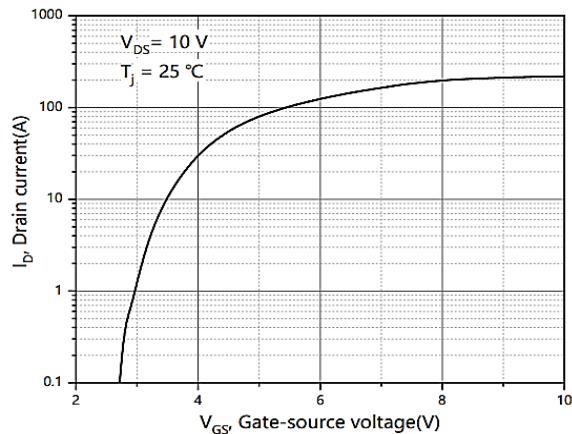


Figure 2. Typ. transfer characteristics

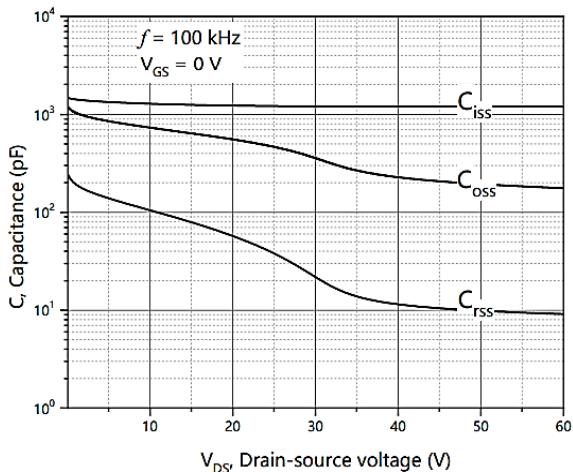


Figure 3. Typ. capacitances

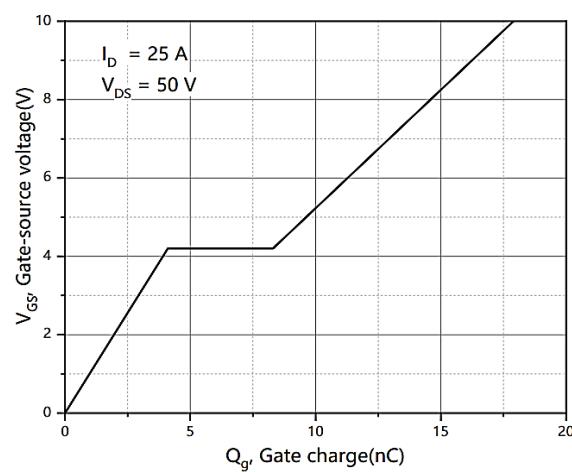


Figure 4. Typ. gate charge

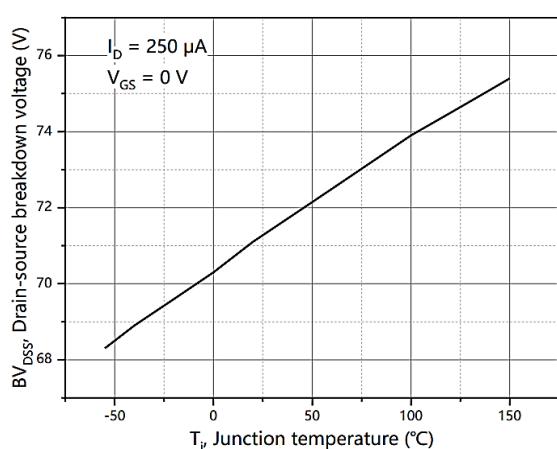


Figure 5. Drain-source breakdown voltage

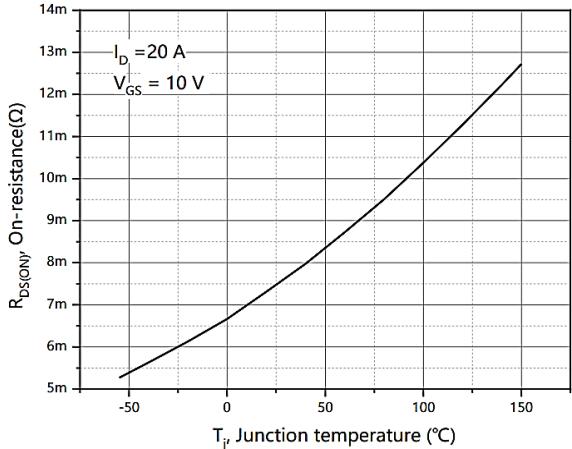


Figure 6. Drain-source on-state resistance

Ratings and Characteristic Curves

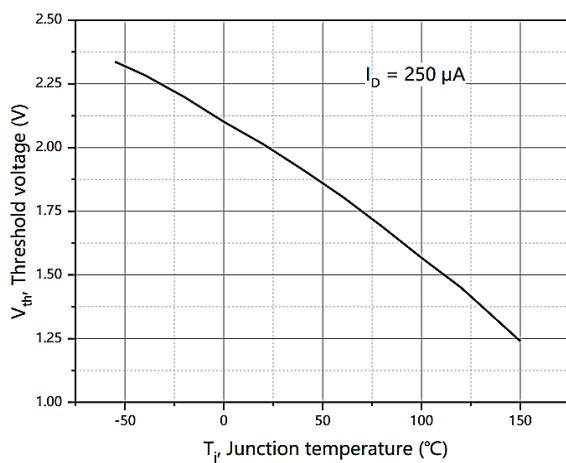


Figure 7. Threshold voltage

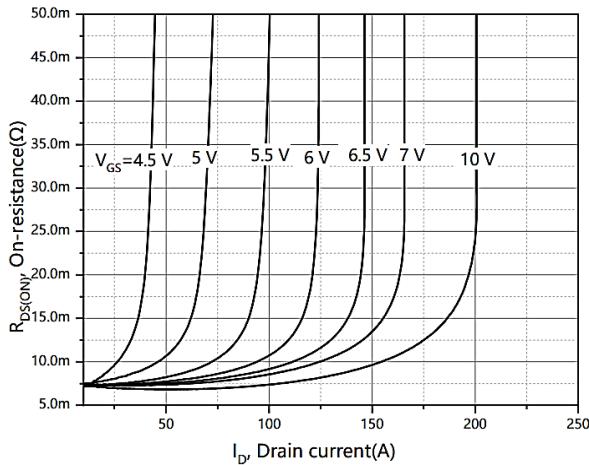


Figure 9. Drain-source on-state resistance

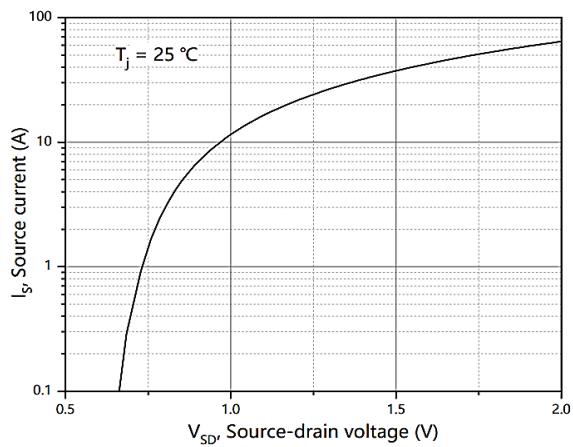


Figure 8. Forward characteristic of body diode

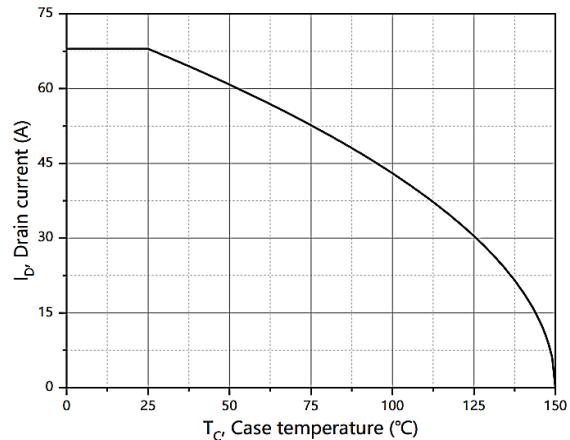


Figure 10. Drain current

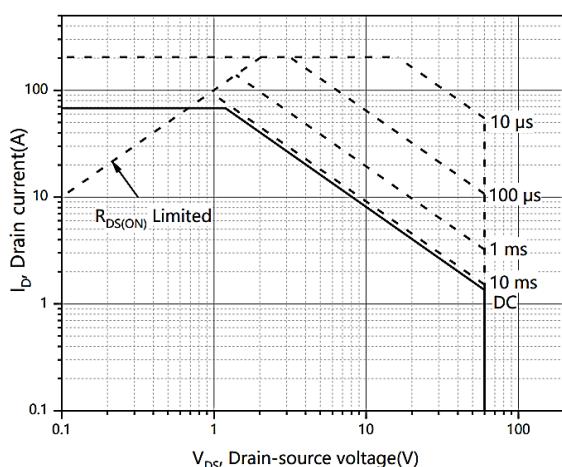


Figure 11. Safe operation area $T_c=25$ °C

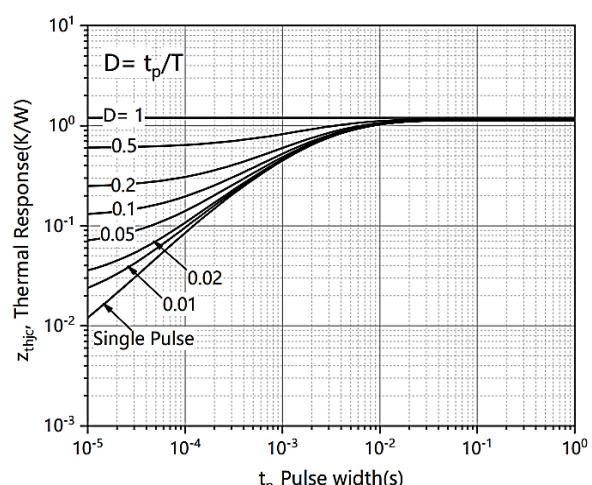
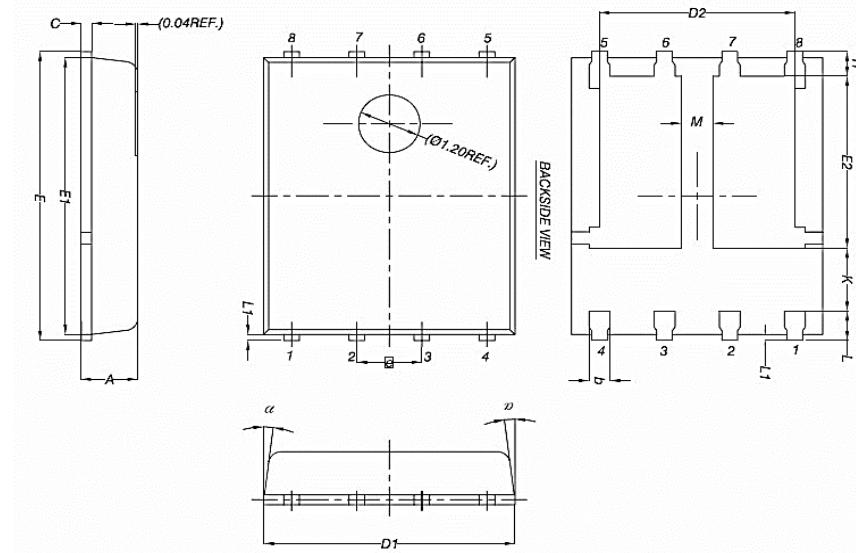


Figure 12. Max. transient thermal impedance

Package Outline Dimensions Millimeters

PDFN5*6-8L



Symbol	Common mm		
	Mim	Nom	Max
A	0.90	1.00	1.10
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	3.30	3.45
E2	3.38	3.05	3.20
e	1.27BSC		
H	0.41	0.51	0.61
K	1.10	--	--
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
M	0.50	--	--
a	0°	--	12°